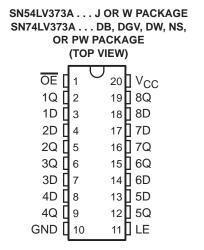
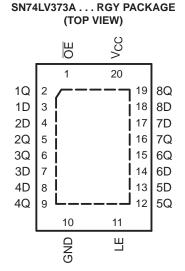
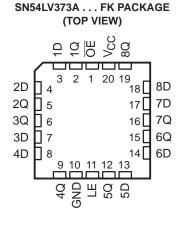
SCLS407J - APRIL 1998 - REVISED APRIL 2005

- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 8.5 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2.3 V at V_{CC} = 3.3 V, T_A = 25°C
- Support Mixed-Mode Voltage Operation on All Ports
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)







description/ordering information

The 'LV373A devices are octal transparent D-type latches designed for 2-V to 5.5-V V_{CC} operation.

ORDERING INFORMATION

TA	PACK	AGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QFN – RGY	Reel of 1000	SN74LV373ARGYR	LV373A
	0010 014	Tube of 25	SN74LV373ADW	11/0704
	SOIC – DW	Reel of 2500	SN74LV373ADWR	LV373A
	SOP - NS	Reel of 2000	SN74LV373ANSR	74LV373A
4000 4 0500	SSOP – DB	Reel of 2000	SN74LV373ADBR	LV373A
–40°C to 85°C		Tube of 70	SN74LV373APW	
	TSSOP - PW	Reel of 2000	SN74LV373APWR	LV373A
		Reel of 250	SN74LV373APWT	
	TVSOP - DGV	Reel of 2000	SN74LV373ADGVR	LV373A
	VFBGA – GQN	Reel of 1000	SN74LV373AGQNR	LV373A
	CDIP – J	Tube of 20	SNJ54LV373AJ	SNJ54LV373AJ
–55°C to 125°C	CFP – W	Tube of 85	SNJ54LV373AW	SNJ54LV373AW
	LCCC - FK	Tube of 55	SNJ54LV373AFK	SNJ54LV373AFK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SCLS407J - APRIL 1998 - REVISED APRIL 2005

description/ordering information (continued)

While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable (OE) input can be used to place the eight outputs in either a normal logic state (high or low) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, OE should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

GQN PACKAGE (TOP VIEW) В \bigcirc 0000С 0000D \bigcirc Ε

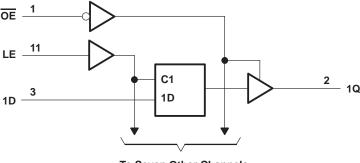
terminal assignments

	1	2	3	4
Α	1Q	OE	Vcc	8Q
В	2D	7D	1D	8D
С	3Q	2Q	6Q	7Q
D	4D	5D	3D	6D
Е	GND	4Q	LE	5Q

FUNCTION TABLE (each latch)

	INPUTS		OUTPUT
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q_0
Н	Χ	Χ	Z

logic diagram (positive logic)



To Seven Other Channels

Pin numbers shown are for the DB, DGV, DW, FK, J, NS, PW, RGY, and W packages.



SCLS407J - APRIL 1998 - REVISED APRIL 2005

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Voltage range applied to any output in the high-impedance or	
power-off state, V _O (see Note 1)	0.5 V to 7 V
Output voltage range, V _O (see Notes 1 and 2)0.5	
Input clamp current, $I_{ K }(V_{ I } < 0)$	–20 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±35 mA
Continuous current through V _{CC} or GND	
Package thermal impedance, θ _{JA} (see Note 3): DB package	
(see Note 3): DGV package	
(see Note 3): DW package	
(see Note 3): GQN package	
(see Note 3): NS package	
(see Note 3): PW package	83°C/W
(see Note 4): RGY package	37°C/W
Storage temperature range, T _{stq}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 5.5 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.
- 4. The package thermal impedance is calculated in accordance with JESD 51-5.



SCLS407J - APRIL 1998 - REVISED APRIL 2005

recommended operating conditions (see Note 5)

			SN54L	V373A	SN74L	.V373A	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2	5.5	2	5.5	V
		V _{CC} = 2 V	1.5		1.5		
.,		V _{CC} = 2.3 V to 2.7 V	V _{CC} ×0.7		V _{CC} × 0.7		.,
V_{IH}	High-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	V _{CC} × 0.7		$V_{CC} \times 0.7$		V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	V _{CC} × 0.7		$V_{CC} \times 0.7$		
		V _{CC} = 2 V		0.5		0.5	
.,		V _{CC} = 2.3 V to 2.7 V		V _{CC} × 0.3		V _{CC} × 0.3	.,
V_{IL}	Low-level input voltage	V _{CC} = 3 V to 3.6 V		V _{CC} ×0.3		V _{CC} × 0.3	V
		V _{CC} = 4.5 V to 5.5 V		V _{CC} ×0.3		V _{CC} × 0.3	
٧ı	Input voltage	<u>.</u>	0	5.5	0	5.5	V
.,		High or low state	0	⁴ √VCC	0	VCC	.,
VO	Output voltage	3-state	0 🗡	5.5	0	5.5	V
		V _{CC} = 2 V	5	-50		-50	μΑ
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	20	-2		-2	
IOH	High-level output current	V _{CC} = 3 V to 3.6 V	Q	-8		-8	mA
		V _{CC} = 4.5 V to 5.5 V		-16		-16	
		V _{CC} = 2 V		50		50	μΑ
		V _{CC} = 2.3 V to 2.7 V		2		2	
IOL	Low-level output current	V _{CC} = 3 V to 3.6 V		8		8	mA
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		16		16	
		V _{CC} = 2.3 V to 2.7 V		200		200	
Δt/Δν	Input transition rise or fall rate	V _{CC} = 3 V to 3.6 V		100		100	ns/V
		V _{CC} = 4.5 V to 5.5 V		20		20	
TA	Operating free-air temperature	-	-55	125	-40	85	°C

NOTE 5: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

		l .,	SN54	4LV373A		SN74	LV373A	١	
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1			V _{CC} -0.1			
	$I_{OH} = -2 \text{ mA}$	2.3 V	2			2			V
VOH	$I_{OH} = -8 \text{ mA}$	3 V	2.48			2.48			V
	$I_{OH} = -16 \text{ mA}$	4.5 V	3.8	18	3	3.8			
	I _{OL} = 50 μA	2 V to 5.5 V		, S	0.1			0.1	
V - :	$I_{OL} = 2 \text{ mA}$	2.3 V		2	0.4			0.4	V
VOL	$I_{OL} = 8 \text{ mA}$	3 V		5	0.44			0.44	V
	I _{OL} = 16 mA	4.5 V	26	5	0.55			0.55	
lį	$V_I = 5.5 \text{ V or GND}$	0 to 5.5 V	60%		±1			±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V	Q.		±5			±5	μΑ
lcc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			20			20	μΑ
l _{off}	V_I or $V_O = 0$ to 5.5 V	0			5			5	μΑ
Ci	V _I = V _{CC} or GND	3.3 V		2.9			2.9		pF

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



SCLS407J - APRIL 1998 - REVISED APRIL 2005

timing requirements over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

			T _A = 2	25°C	SN54L	V373A	SN74L	√373A	
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t _W	Pulse duration, LE high		6		6.5	W.U	6.5		ns
t _{su}	Setup time, data before LE \downarrow	High or low	4.5		5	TIL	5		ns
th	Hold time, data after LE↓	High or low	1.5		1.5		1.5		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

			$T_A = 2$	25°C	SN54L	/373A	SN74L\	/373A	LINUT
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t _W	Pulse duration, LE high		5		5	N.U	5		ns
t _{su}	Setup time, data before LE↓	High or low	4		4	JIV.	4		ns
th	Hold time, data after LE↓	High or low	1		d		1		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

			T _A = 2	25°C	SN54L	V373A	SN74L\	/373A	LINUT
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t _W	Pulse duration, LE high		5		5	W.U	5		ns
t _{su}	Setup time, data before LE↓	High or low	4		4	TIL	4		ns
th	Hold time, data after LE↓	High or low	1		(d)		1		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V \pm 0.2 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	T,	Վ = 25 °C	;	SN54L\	/373A	SN74L\	/373A		
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
	D	Q			8.3*	15.2*	1*	17*	1	17		
^t pd	LE	Q	0 45		9.1*	15.7*	1*	19*	1	19		
t _{en}	ŌE	Q	C _L = 15 pF		8.9*	15.8*	1*	19*	1	19	ns	
^t dis	ŌĒ	Q			6.2*	12.6*	1*	15*	1	15		
	D	Q			10.4	18	1	21	1	21		
^t pd	LE	Q			11.1	18.6)77 _G	22	1	22		
t _{en}	ŌĒ	Q	C _L = 50 pF	C _L = 50 pF		10.9	18.8	06/1	22	1	22	ns
^t dis	ŌĒ	Q			8.3	17.4	1	19	1	19		
t _{sk(o)}						2				2		

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



SCLS407J - APRIL 1998 - REVISED APRIL 2005

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

	FROM	то	LOAD	T,	չ = 25°C	;	SN54L	/373A	SN74L\	/373A				
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT			
4 .	D	Q			5.8*	11.4*	1*	13.5*	1	13.5				
^t pd	LE	Q	0. 45		6.4*	11*	1*	13*	1	13				
t _{en}	ŌE	Q	C _L = 15 pF		6.3*	11.4*	1*	13.5*	1	13.5	ns			
^t dis	ŌĒ	Q			4.7*	10*	1*	12*	1	12				
4	D	Q			7.3	14.9	1	17	1	17				
^t pd	LE	Q	1]				7.8	14.5	770	16.5	1	16.5	
t _{en}	ŌĒ	Q	C _L = 50 pF		7.7	14.9	0 1	17	1	17	ns			
^t dis	ŌĒ	Q			6	13.2	1	15	1	15				
tsk(o)						1.5				1.5				

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED		LOAD	T,	Δ = 25°C	;	SN54L\	/373A	SN74L	/373A		
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	D	Q			4.1*	7.2*	1*	8.5*	1	8.5	
^t pd	LE	Q	0 45 5		4.5*	7.2*	1*	8.5*	1	8.5	
t _{en}	ŌĒ	Q	$C_L = 15 pF$		4.5*	8.1*	1*	9.5*	1	9.5	ns
^t dis	ŌĒ	Q			3.3*	7.2*	1*	8.5*	1	8.5	
	D	Q			5.1	9.2	1	10.5	1	10.5	
^t pd	LE	Q			5.5	9.2	770	10.5	1	10.5	
t _{en}	ŌĒ	Q	C _L = 50 pF		5.5	10.1	Q ⁰ 1	11.5	1	11.5	ns
^t dis	ŌĒ	Q			4	9.2	1	10.5	1	10.5	
tsk(o)						1				1	

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.

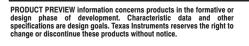
noise characteristics, $V_{CC} = 3.3 \text{ V}$, $C_L = 50 \text{ pF}$, $T_A = 25^{\circ}\text{C}$ (see Note 6)

24244		SN	UNIT		
	PARAMETER				
VOL(P)	Quiet output, maximum dynamic V _{OL}		0.6	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.6	-0.8	V
V _{OH(V)}	Quiet output, minimum dynamic V _{OH}		2.9		V
VIH(D)	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

NOTE 6: Characteristics are for surface-mount packages only.

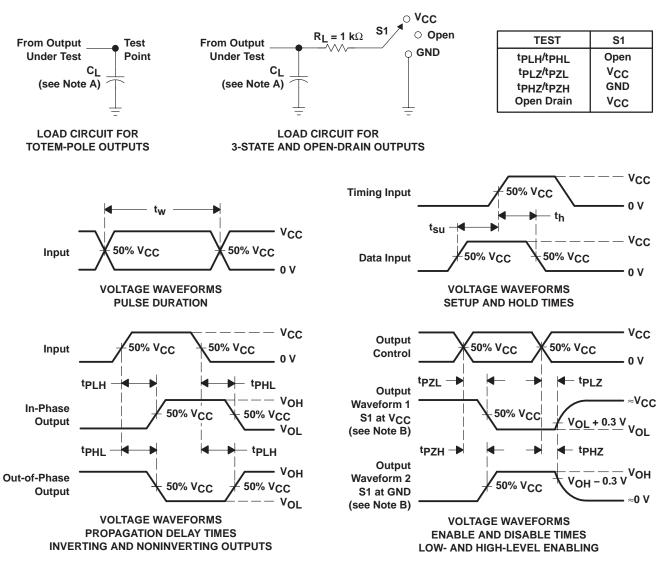
operating characteristics, T_A = 25°C

PARAMETER			TEST CONDITIONS		VCC	TYP	UNIT	
ſ	<u> </u>	Down discinstian constitutes	Outputs anabled	C. 50 pF	f 40 MH=	3.3 V	17.4	
ı	Cpd	Power dissipation capacitance	Outputs enabled	$C_L = 50 \text{ pF}, f = 10 \text{ MHz}$	5 V	19.5	pF	





PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, $Z_Q = 50 \Omega$, $t_f \leq 3$ ns, $t_f \leq 3$ ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzi and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms







ti.com 5-Jul-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
SN74LV373ADBR	ACTIVE	SSOP	DB	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LV373ADBRE4	ACTIVE	SSOP	DB	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74LV373ADGVR	ACTIVE	TVSOP	DGV	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV373ADGVRE4	ACTIVE	TVSOP	DGV	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV373ADW	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74LV373ADWE4	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74LV373ADWR	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74LV373ADWRE4	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74LV373AGQNR	ACTIVE	VFBGA	GQN	20	1000	TBD	SNPB	Level-1-240C-UNLIM
SN74LV373ANSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV373ANSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV373APW	ACTIVE	TSSOP	PW	20	70	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV373APWE4	ACTIVE	TSSOP	PW	20	70	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV373APWR	ACTIVE	TSSOP	PW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV373APWRE4	ACTIVE	TSSOP	PW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV373APWRG4	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV373APWT	ACTIVE	TSSOP	PW	20	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV373APWTE4	ACTIVE	TSSOP	PW	20	250	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74LV373ARGYR	ACTIVE	QFN	RGY	20	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR

 $^{^{(1)}}$ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

5-Jul-2005

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

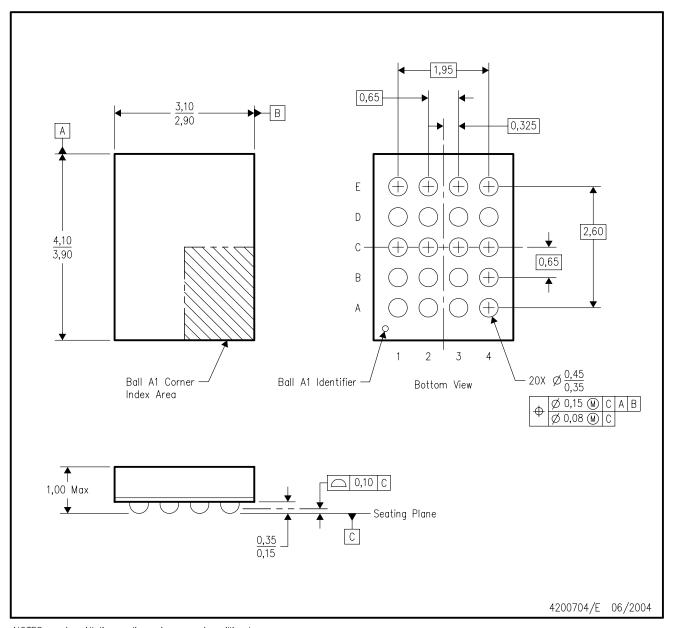
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

GQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225 variation BC.
- D. This package is tin-lead (SnPb). Refer to the 20 ZQN package (drawing 4204492) for lead-free.



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



DW (R-PDSO-G20)

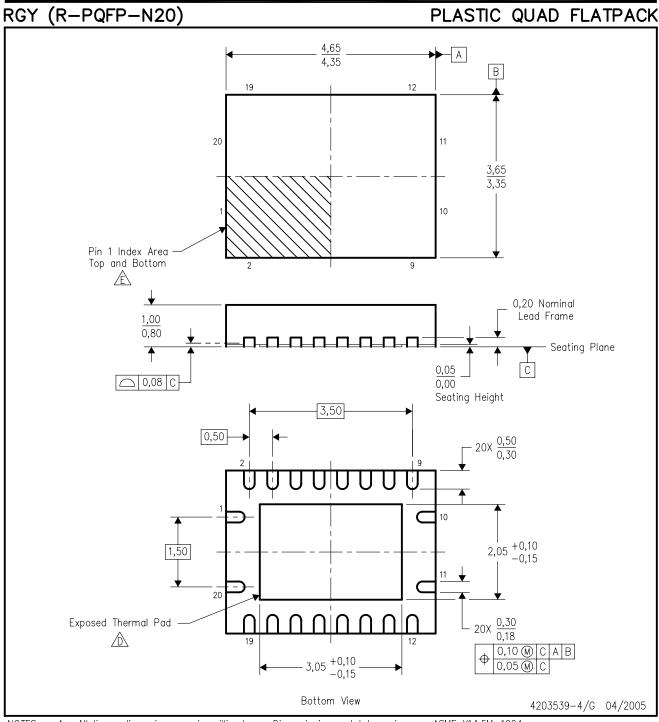
PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.





NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) package configuration.
- The package thermal pad must be soldered to the board for thermal and mechanical performance.
- Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
- F. Package complies to JEDEC MO-241 variation BC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2005, Texas Instruments Incorporated